### Dicing tape

ARIS provides the best possible solution to you in the semiconductor

manufacturing process with the following features.

> Specially designed adhesive
Special adhesive with less surface contamination

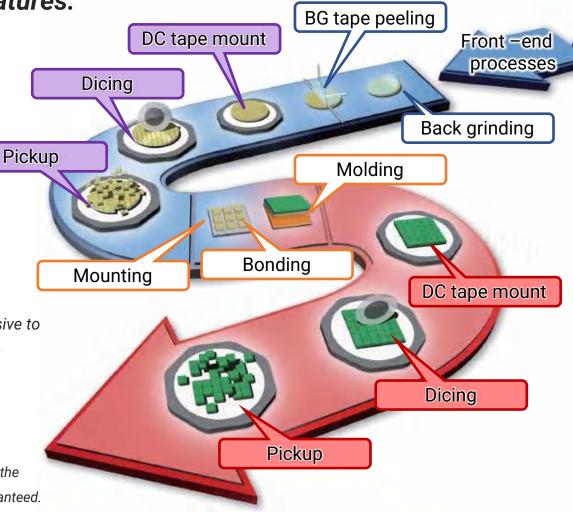
> Eco-Friendly backing

**Environmentally friendly backing material (Polyolefin)** 

The needs of technology for dicing process have been increasing by recent downsized electronic devices and expansion of demand for semiconductor chips. We will tailor to meet your needs.

No.6360 series is a dicing tape formed by coating a UV release adhesive to a highly isotopic polyolefin base material. This tape can firmly secure workpieces during dicing, and chips can be easily picked up through irradiation with UV light.

- Specification is subject to change without notice.
- All the figures, technical information and recommendation stated above are on the basis of the tests we believe to be reliable, but the accuracy there of is not guaranteed.



Design/masking

processes

# Dicing tape for wafer | Line up

Item		6360-00	6360-05	6360-20	6360-50	6366-00	6368-00
Base film		PO	PO	PO	PO	PO	PO
Thickness [µm]	Base film	90	90	90	90	100	80
	Adhesive	010	୍ର 5	010	010	010	5
	Total	100	95	100	100	110	85
Peel strength [N/10mm]	Initial	2.80	1.80	3.30	2.80	0.88	2.40
	After UV	0.23	0.07	0.30	0.08	0.08	0.09
Tensile strength [N/10mm]	MD	015	22	015	015	019	22
	TD	013	017	013	013	019	21
Elongation [%]	MD	580	740	580	580	600	1,600
	TD	650	760	650	650	850	2,050
Remark		Standard	Limits the chipping	High adhesion	Easy pick-up	Limits the chipping	High expandability

## Dicing tape for Substrate, Glass, LED | Line up

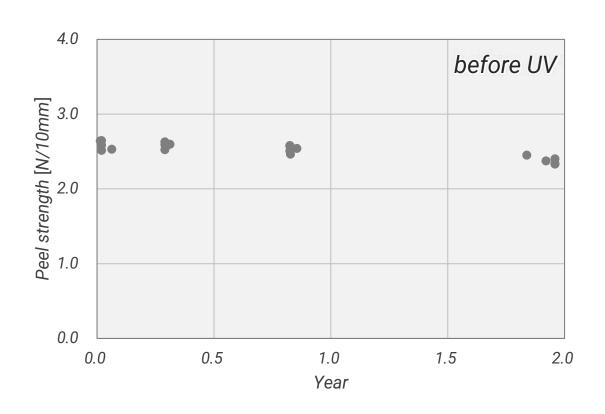
Item		6360-15	6360-25	6360-55	6360-95	6365-61	6365-62
Base film		PO	PO	PO	P0	PO	PO
Thickness [µm]	Base film	150	150	150	150	140	140
	Adhesive	010	010	010	20	010	20
	Total	160	160	160	170	150	160
Peel strength [N/10mm]	Initial	3.00	3.50	2.90	4.10	2.80	3.80
	After UV	0.22	0.24	0.09	0.10	0.08	0.08
Tensile strength [N/10mm]	MD	30	30	(30	(30	(30	30
	TD	30	(30	(30	(30	(30	30
Elongation [%]	MD	760	760	760	760	800	800
	TD	800	800	800	800	800	800
Remark		Standard	High adhesion	Easy pick-up	High adhesion Easy pick-up	Limits the burr Easy pick-up	Limits the burr High adhesion Easy pick-up

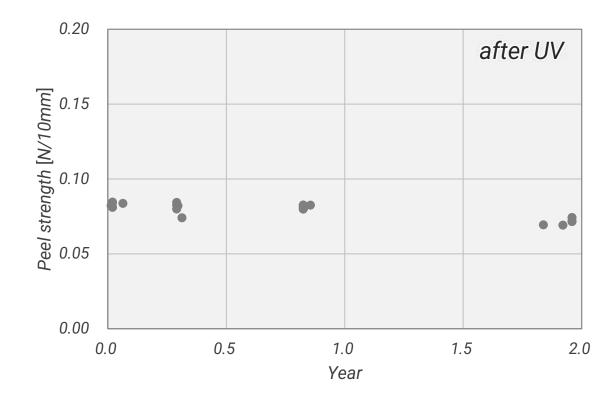
## Dicing tape | Stability

Test Condition(1)

Tape : No.6360-50

Storage  $\rightarrow$  <u>Tape laminate</u>  $\rightarrow$  Measurement



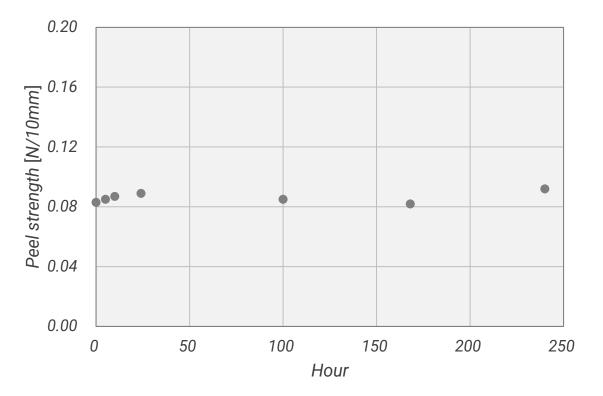


### **Dicing tape** | Stability

Test Condition(2)

Tape : No.6360-50

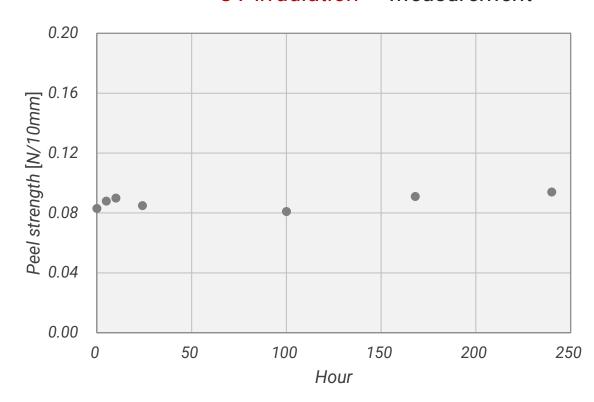
<u>Tape laminate</u>  $\rightarrow$  <u>UV irradiation</u>  $\rightarrow$  Storage  $\rightarrow$  Measurement



Test Condition(3)

Tape : No.6360-50

<u>Tape laminate</u>  $\rightarrow$  Storage  $\rightarrow$  UV irradiation  $\rightarrow$  Measurement

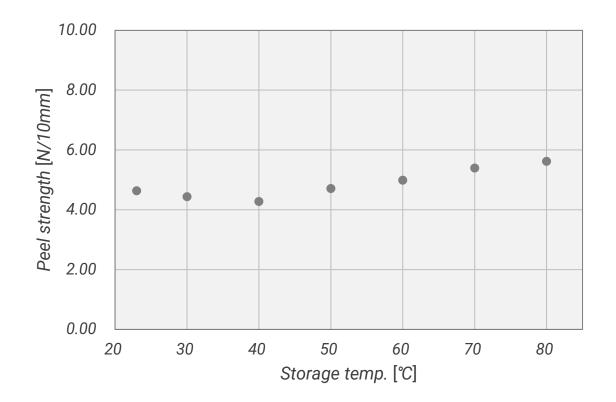


## **Dicing tape** | Heat resistant

**Test Condition** 

Tape : No.6360-95

Tape laminate(23°C)  $\rightarrow$  Storage at each temp.(1h)  $\rightarrow$  Storage at 23°C(30min.)  $\rightarrow$  Measurement(23°C)



Tape laminate(23°C)  $\rightarrow$  UV irradiation

- $\rightarrow$  Storage at each temp.(1h)  $\rightarrow$  Storage at 23°C(30min.)
- $\rightarrow$  Measurement(23°C)

